SCBS188C - FEBRUARY 1991 - REVISED JANUARY 1997

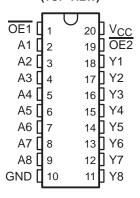
- State-of-the-Art *EPIC-IIB™* BiCMOS Design **Significantly Reduces Power Dissipation**
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 500 mA Per **JEDEC Standard JESD-17**
- Typical V<sub>OLP</sub> (Output Ground Bounce) < 1 V at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$
- High-Drive Outputs (-32-mA I<sub>OH</sub>, 64-mA I<sub>OL</sub>)
- **Package Options Include Plastic** Small-Outline (DW), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK), Plastic (N) and Ceramic (J) DIPs, and Ceramic Flat (W) Package

#### description

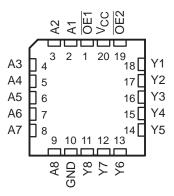
The 'ABT540 octal buffers and line drivers are ideal for driving bus lines or buffer memory address registers. The devices feature inputs and outputs on opposite sides of the package that facilitate printed circuit board layout.

The 3-state control gate is a 2-input AND gate with active-low inputs so that if either output-enable (OE1 or OE2) input is high, all corresponding outputs are in the high-impedance state.

SN54ABT540 . . . J OR W PACKAGE SN74ABT540 . . . DB, DW, N, OR PW PACKAGE (TOP VIEW)



SN54ABT540 . . . FK PACKAGE (TOP VIEW)



To ensure the high-impedance state during power up or power down,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABT540 is characterized for operation over the full military temperature range of -55°C to 125°C. The SN74ABT540 is characterized for operation from -40°C to 85°C.

#### **FUNCTION TABLE**

	INPUTS	OUTPUT	
OE1	OE2	Α	Y
L	L	L	Н
L	L	Н	L
Н	X	Χ	Z
X	Н	Χ	Z



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

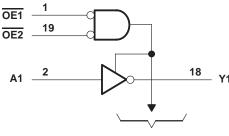
EPIC-IIB is a trademark of Texas Instruments Incorporated



# logic symbol†

#### 1 OE1 19 EN OE2 2 18 Α1 $\nabla$ **Y1** 17 3 **Y2** A2 4 16 А3 **Y3** 5 15 **A4** 6 14 **Y5** Α5 7 13 A6 **Y6** 8 12 **Y7 A7** 9 11 **A8 Y8**

# logic diagram (positive logic)



To Seven Other Channels

# absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V <sub>CC</sub>		$\dots$ -0.5 V to 7 V
Input voltage range, V <sub>I</sub> (see Note 1)		$-0.5 \text{ V to 7 V}$
Voltage range applied to any output in the high	or power-off state, VO	. $-0.5$ V to $5.5$ V
Current into any output in the low state, IO: SNS	54ABT540	96 mA
SN	74ABT540	128 mA
Input clamp current, I <sub>IK</sub> (V <sub>I</sub> < 0)		–18 mA
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0)		–50 mA
Package thermal impedance, $\theta_{JA}$ (see Note 2):	DB package	115°C/W
•	DW package	97°C/W
	N package	67°C/W
	PW package	128°C/W
Storage temperature range, T <sub>stg</sub>		-65°C to 150°C

<sup>‡</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
  - 2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51, except for through-hole packages, which use a trace length of zero.

### recommended operating conditions (see Note 3)

			SN54A	BT540	SN74A	BT540	UNIT
			MIN	MAX	MIN	MAX	UNII
Vcc	Supply voltage		4.5	5.5	4.5	5.5	V
VIH	High-level input voltage		2	J. J.	2		V
VIL	Low-level input voltage		0.8		0.8	V	
٧ <sub>I</sub>	Input voltage		0,4	Vcc	0	VCC	V
IOH	High-level output current		S	-24		-32	mA
loL	Low-level output current	90	48		64	mA	
Δt/Δν	Input transition rise or fall rate	Outputs enabled	Q.	5		5	ns/V
TA	Operating free-air temperature		-55	125	-40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.



<sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

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# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST COND	ī	A = 25°C	;	SN54A	BT540	SN74A	BT540	UNIT	
PARAI	WEIER	I EST CONL	IIIONS	MIN	TYP†	MAX	MIN	MAX	MIN	MAX	UNII
۷ıK		V <sub>CC</sub> = 4.5 V,	I <sub>I</sub> = -18 mA			-1.2		-1.2		-1.2	V
		V <sub>CC</sub> = 4.5 V,	$I_{OH} = -3 \text{ mA}$	2.5			2.5		2.5		
\/a		$V_{CC} = 5 V$ ,	$I_{OH} = -3 \text{ mA}$	3			3		3		V
VOH		V <sub>CC</sub> = 4.5 V	I <sub>OH</sub> = -24 mA	2			2				V
		VCC = 4.5 V	$I_{OH} = -32 \text{ mA}$	2*					2		
Vai		V <sub>CC</sub> = 4.5 V	I <sub>OL</sub> = 48 mA			0.55		0.55			V
VOL		VCC = 4.5 V	I <sub>OL</sub> = 64 mA			0.55*				0.55	V
V <sub>hys</sub>					100			2			mV
lį		V <sub>CC</sub> = 5.5 V,	$V_I = V_{CC}$ or GND			±1		±1		±1	μΑ
lozh		V <sub>CC</sub> = 5.5 V,	$V_0 = 2.7 \text{ V}$			50		<b>4</b> 50		50	μΑ
lozL		$V_{CC} = 5.5 \text{ V},$	$V_0 = 0.5 V$			-50		<b>–</b> 50		-50	μΑ
l <sub>off</sub>		$V_{CC} = 0$ ,	$V_I$ or $V_O \le 4.5 \text{ V}$			±100	3			±100	μΑ
ICEX		$V_{CC} = 5.5 \text{ V}, V_{O} = 5.5 \text{ V}$	Outputs high			50	90	50		50	μΑ
10 <sup>‡</sup>		$V_{CC} = 5.5 \text{ V},$	V <sub>O</sub> = 2.5 V	-50	-100	-180	<b>–</b> 50	-180	-50	-180	mA
			Outputs high		1	250		250		250	μΑ
ICC		$V_{CC} = 5.5 \text{ V}, I_{O} = 0,$ $V_{I} = V_{CC} \text{ or GND}$	Outputs low		24	30		30		30	mA
	_	17 100 01 0112	Outputs disabled		0.5	250		250		250	μΑ
	Data	V <sub>CC</sub> = 5.5 V, One input at 3.4 V,	Outputs enabled			1.5		1.5		1.5	
ΔICC§	inputs	Other inputs at V <sub>CC</sub> or GND	Outputs disabled			0.05		0.05		0.05	mA
	Control inputs	V <sub>CC</sub> = 5.5 V, One input at 3.4 V, Other inputs at V <sub>CC</sub> or GND				1.5		1.5		1.5	
Ci	-	V <sub>I</sub> = 2.5 V or 0.5 V			3						pF
Co		V <sub>O</sub> = 2.5 V or 0.5 V			8						pF

<sup>\*</sup> On products compliant to MIL-PRF-38535, this parameter does not apply.

# switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50$ pF (unless otherwise noted) (see Figure 1)

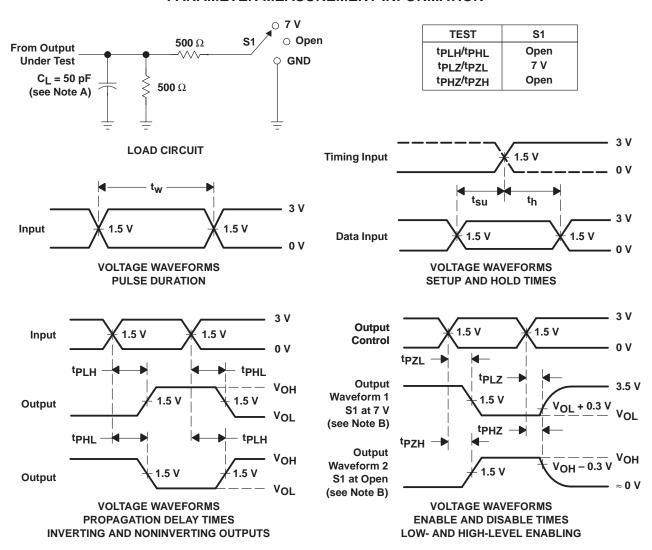
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>(</sub>	CC = 5 V \(\frac{1}{2} = 25°C	', ;	SN54AB1	Γ540	SN74A	BT540	UNIT
	(1141 01)	(0011 01)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	
tPLH	А	V	1	2.9	4.1	1	1/5	1	4.8	ns
t <sub>PHL</sub>	A	T	1	3.1	4.3	1 %	4	1	4.8	115
<sup>t</sup> PZH	ŌĒ		1.1	3.4	4.9	1.1		1.1	5.9	ns
t <sub>PZL</sub>	OE	ı	1.1	3	5.8	32)		1.1	6.4	115
t <sub>PHZ</sub>	ŌĒ		1.5	5.3	6.8	1.5		1.5	7.3	ns
t <sub>PLZ</sub>	OE .	ı	1.2	4.4	5.7	1.2		1.2	6.2	115

<sup>†</sup> All typical values are at  $V_{CC} = 5 \text{ V}$ .

<sup>‡</sup> Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

<sup>§</sup> This is the increase in supply current for each input that is at the specified TTL voltage level rather than V<sub>CC</sub> or GND.

#### PARAMETER MEASUREMENT INFORMATION



NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O = 50~\Omega$ ,  $t_f \leq$  2.5 ns,  $t_f \leq$  2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms









### **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SN74ABT540DBLE	OBSOLETE	SSOP	DB	20		TBD	Call TI	Call TI
SN74ABT540DBR	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT540DBRE4	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT540DBRG4	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT540DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT540DWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT540DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT540DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT540DWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT540DWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT540N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74ABT540NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74ABT540NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT540NSRE4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT540NSRG4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

<sup>&</sup>lt;sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <a href="http://www.ti.com/productcontent">http://www.ti.com/productcontent</a> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.



# PACKAGE OPTION ADDENDUM

18-Sep-2008

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# TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

# QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



### \*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ABT540DBR	SSOP	DB	20	2000	330.0	16.4	8.2	7.5	2.5	12.0	16.0	Q1
SN74ABT540DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1
SN74ABT540NSR	SO	NS	20	2000	330.0	24.4	8.2	13.0	2.5	12.0	24.0	Q1





\*All dimensions are nominal

7 till dilliteriorette die memilia							
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ABT540DBR	SSOP	DB	20	2000	346.0	346.0	33.0
SN74ABT540DWR	SOIC	DW	20	2000	346.0	346.0	41.0
SN74ABT540NSR	SO	NS	20	2000	346.0	346.0	41.0

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